



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2818
#4
Amatt B
Kin Jones
1/6/03

In re the Application of: Smith et al.

Docket No.: TI-29811

Serial No.: 09/975,639

Art Unit: 2818

Filed: 10/11/01

Examiner: Hoang, Quoc

Title: Hydrogen Plasma Photoresist Strip And Polymeric Residue Cleanup Process
For Low Dielectric Constant Materials

AMENDMENT UNDER 37 CFR 1.111

December 20, 2002

Assistant Commissioner
for Patents
Washington, D. C. 20231

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)	
I hereby certify that the above correspondence is being deposited	
with the	U.S. Postal Service on
<u>12-20-02</u> as First Class Mail in an	
envelope addressed to: Assistant Commissioner for Patents,	
Washington, D.C.	
<u>Karen Vertz</u>	<u>12-20-02</u>
Karen Vertz	Date

In response to the Office Action, dated 09/24/02, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

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TECHNOLOGY CENTER 2800